



ARC 2022

The 18th International Symposium on Applied Reconfigurable Computing 19-20 Sep, Tsinghua University Beijing, China (Virtually)

Call for Papers

With the great surge of computing demands from various domains, reconfigurable computing has been playing more and more important roles, via providing customizing solutions and sophisticated hardware operations for better time-to-solution and energy-solution. More cutting-edge reconfigurable techniques have also been widely studied, to bring revolutionary breakthroughs. ARC 2022 aims to bring together researchers and practitioners of reconfigurable computing with an emphasis on practical applications of this promising technology.

The ARC 2022 proceedings will be published as a volume in Springer's Lecture Notes in Computer Science (LNCS) series, and will also be available through the SpringerLink online service.



Organizers

General Chair

Yu Wang,
Tsinghua University, China

Program Chairs

Wei Xue,
Tsinghua University, China
Thomas Chau,
Samsung AI Centre, UK

Local Chairs

Lin Gan, Mengxue Qi
Tsinghua University, China

Proceeding Chair

Yun Liang,
Peking University, China

Journal Special Issues

Zhao Liu
NSCC-Wuxi, China

Finance & Sponsor Chairs

Yan Zhang
Tsinghua University, China

Web Chair

Shuo Li,
Tsinghua University, China

Important date

System Open: April 1st, 2022 Notification: Jun. 17, 2022
Submission Due: April 20, 2022 Camera-Ready: July 18, 2022

Web: <https://nicsefc.ee.tsinghua.edu.cn/detail.html?id=1030>

Topics of Interest

Design Methods & Tools

- High-level Languages & Compilations
- Simulation & Synthesis
- Estimation Techniques
- Design Space Exploration
- Run-Time Systems & Virtualization

Applications

- Security & Cryptography
- Time Sensitive/Critical Networks
- Big Data, HPC, Event Processing
- Embedded Computing & DSP
- Robotics, Space, Bioinformatics, Automotive
- Safety & Mission Critical Systems
- Deep Learning & Neural Networks

Architectures

- Self-adaptive Systems
- Heterogeneous & Embedded MPSoCs
- Low-Power Designs
- Approximate Computing
- Fine-/Coarse-/Mixed-grained
- Interconnect (NoCs, ...)
- Resilient & Fault Tolerant
- Close-to-Sensor & Close-to-Memory Computing

Trends (in)

- Teaching RC
- Surveys and Future Trends
- Benchmarks
- Emerging Technologies
- Cyberphysical Systems

